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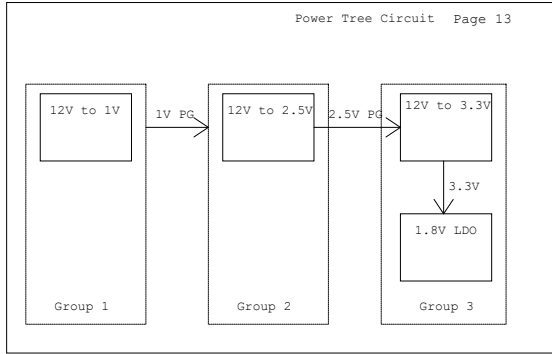
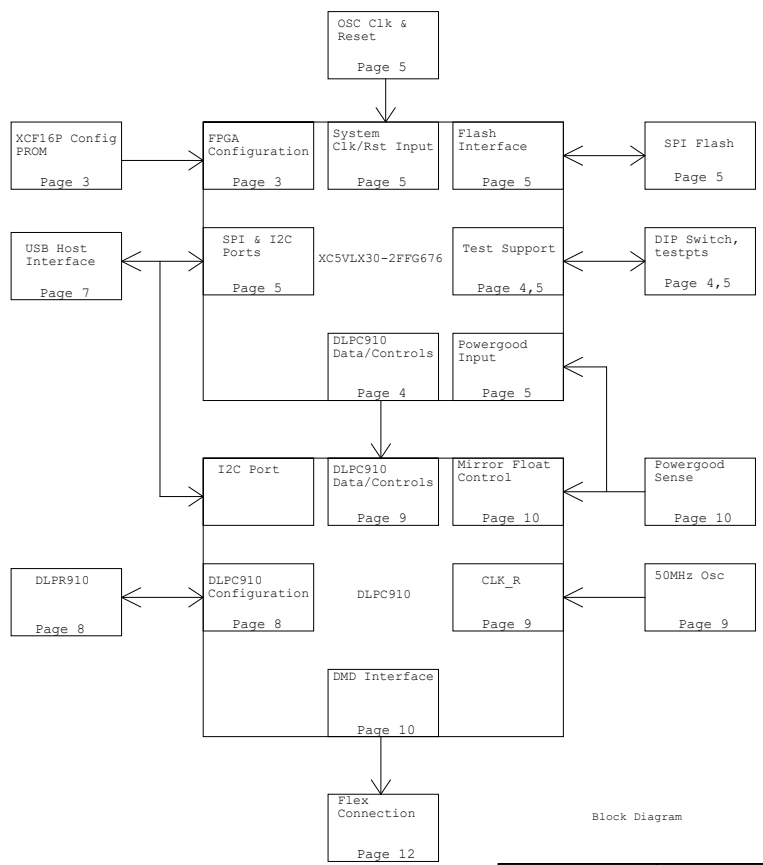
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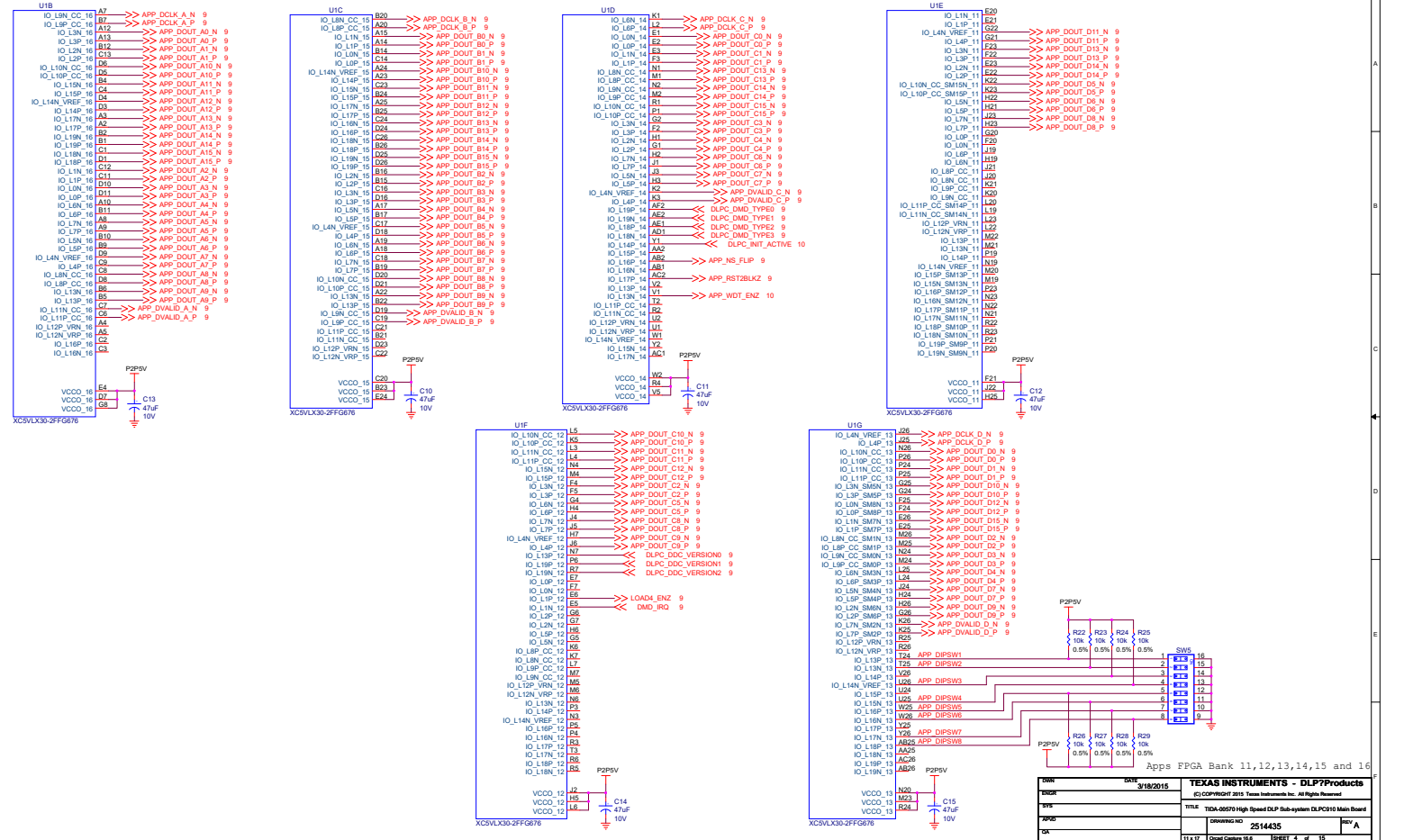
4/20/2015

DATE	3/18/2015	TEXAS INSTRUMENTS - DLP7Products	
DESIGNER		(C) COPYRIGHT 2015 Texas Instruments Inc. All Rights Reserved	
ISS		TITLE	TDA06570 High-Speed DLP Subsystem DLP6310 Mask Board
APP'D		DRAWING NO	2514435
QA		DATE	3/18/2015
		SHEET 1 of 15	



Block Diagram

DATE	3/18/2015	TEXAS INSTRUMENTS - DLP7Products	
DESIGNER		© COPYRIGHT 2015 Texas Instruments Inc. All Rights Reserved	
TITLE		TIDA-05570 High Speed DLP Sub-system DLPC910 Mask Board	
REV		DRAWING NO	2514435
DATE	11.4.17	Drawn/Checked/Rev	SECRET 2 of 15



Apps FPGA Bank 11,12,13,14,15 and 16

Bank	Device	Part	Rev
11	11A	11A	1
12	12A	12A	1
13	13A	13A	1
14	14A	14A	1
15	15A	15A	1
16	16A	16A	1

DATE: 3/18/2015

TEXAS INSTRUMENTS - DLP7Products

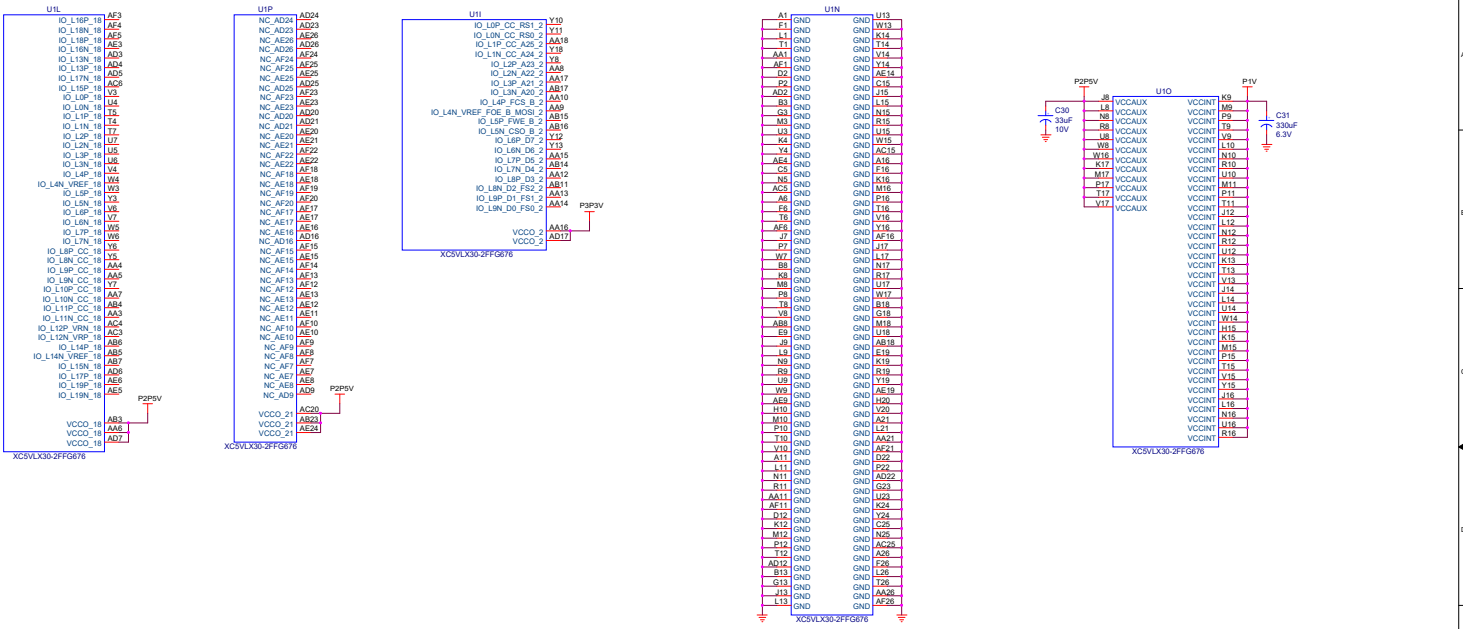
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TITLE: TIDA-06570 High-Speed DLP Sub-system DLP-C310 Main Board

DESIGNED BY: 2514435

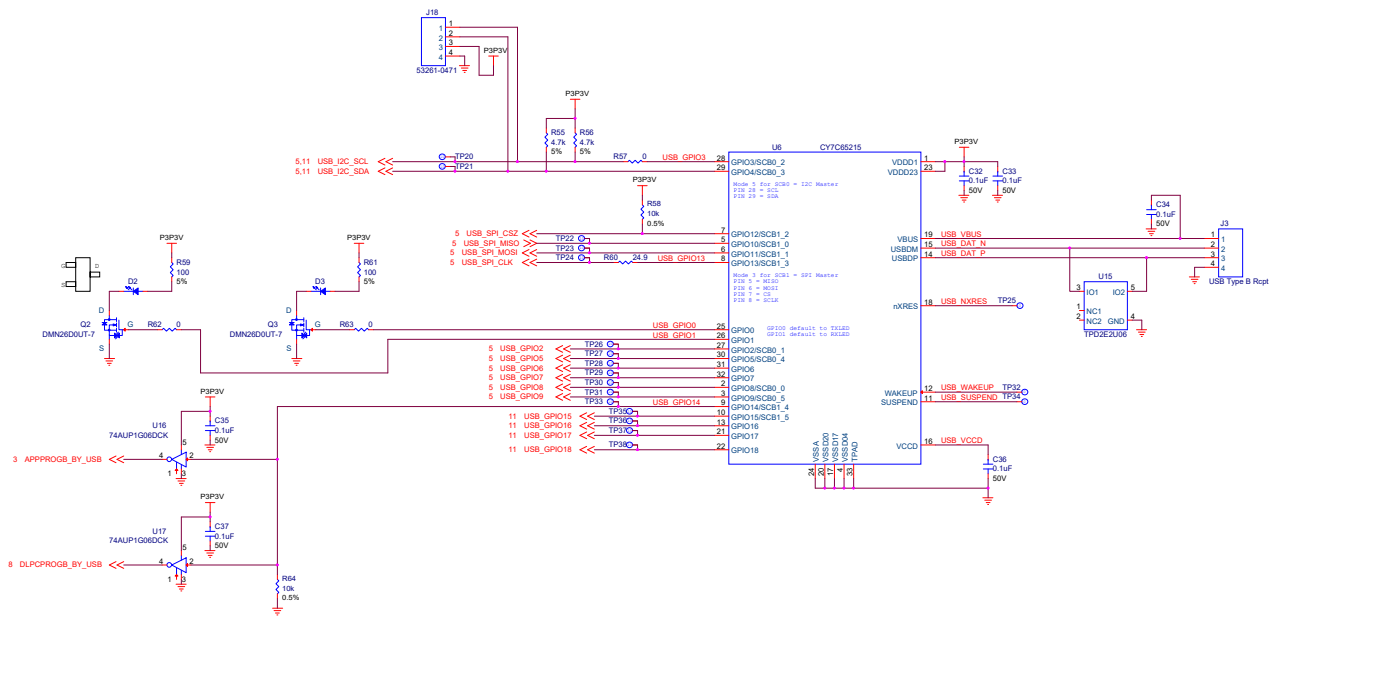
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11 x 17 Sheet Capture 16.8 SHEET 4 of 15



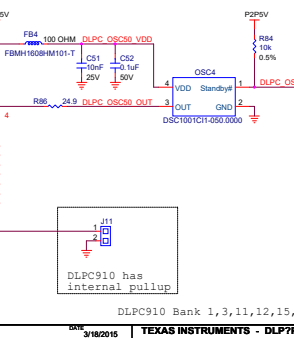
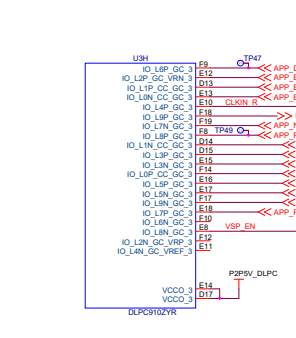
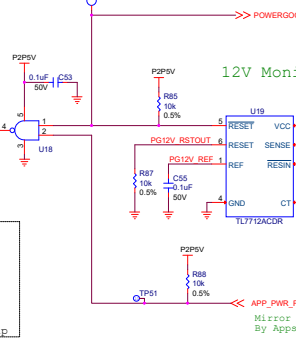
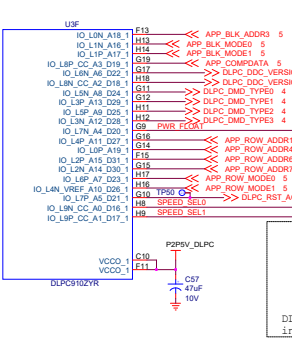
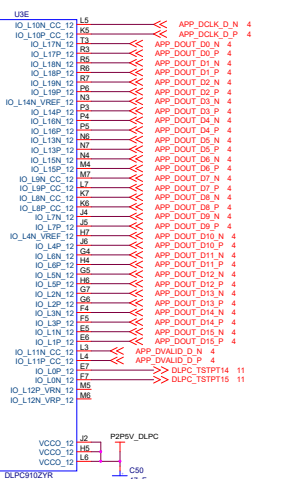
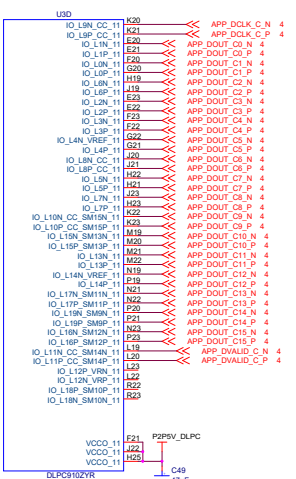
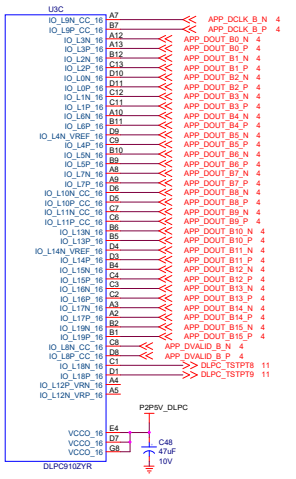
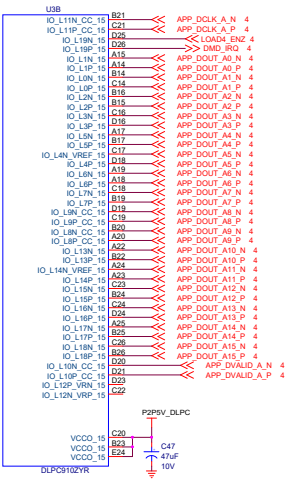
Apps FPGA Power/Ground and Unused Banks

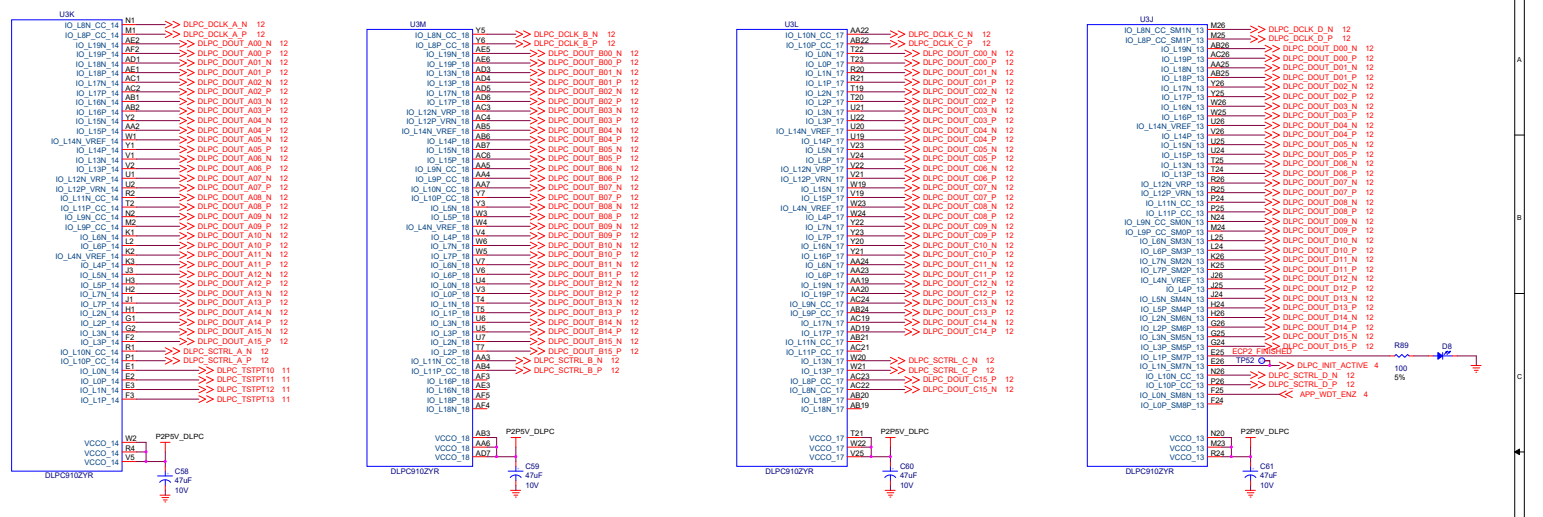
DATE	3/18/2015	TEXAS INSTRUMENTS - DLP7Products	
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TITLE	TDA05570 High Speed DLP Sub-system DLP030 Mask Board		
REV		DRAWING NO	2514435
DATE	11/4/17	Sheet Count	16 of 15



USB Interface

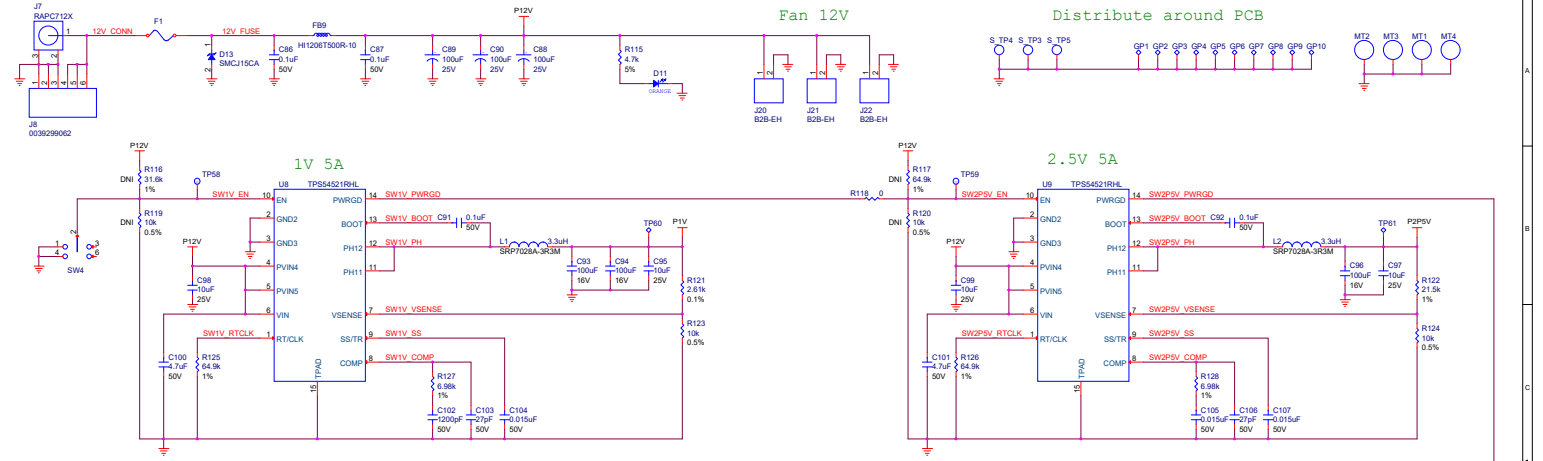
DATE	3/18/2015	TEXAS INSTRUMENTS - DLP7Products
DESIGNER		(C) COPYRIGHT 2015 Texas Instruments Inc. All Rights Reserved
TITLE		TIDA00570 High-Speed DLP Subsystem DLP3010 Mask Board
REV		ISSUING NO 2514435
FILE		11 of 17 Sheet 7 of 15



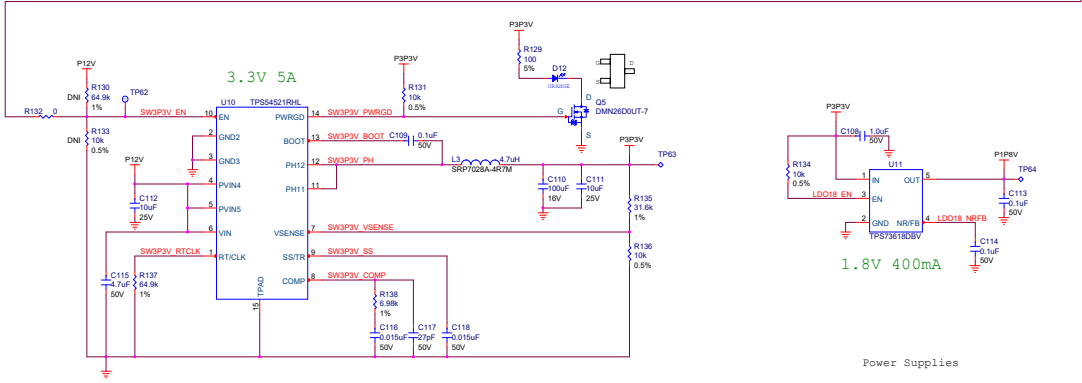
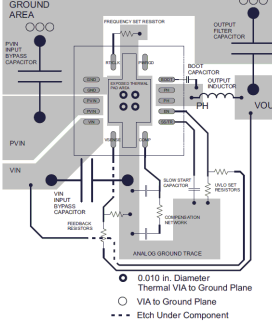


DLP_C910 Bank 13,14,17,18

DATE	3/18/2015	TEXAS INSTRUMENTS - DLP7Products	
DESIGNER		© COPYRIGHT 2015 Texas Instruments Inc. All Rights Reserved	
TITLE	TDA05075 High Speed DLP Sub-system DLP_C910 Mask Board	ISSUE	100
REVISED		DRAWING NO	2514435
DATE		REV	A
11 of 17 - Omni Cadsoft 16.4		SHEET 10 of 15	



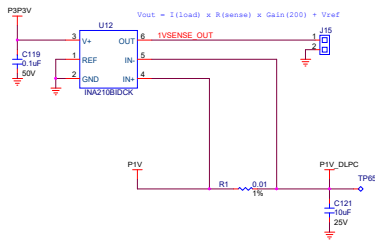
TPS54521 Layout Guideline



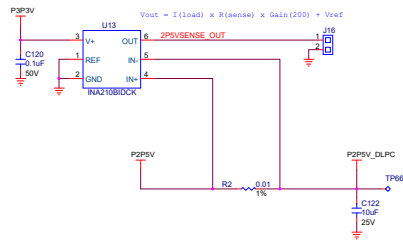
Power Supplies

DATE	3/18/2015	TEXAS INSTRUMENTS - DLP7Products
DESIGNER		© COPYRIGHT 2015 Texas Instruments Inc. All Rights Reserved
TITLE	TDA06570 High Speed DLP Sub-system DLP7C10 Main Board	
DESIGNER/NO	2514435	REV A
DATE	11/17/17	Sheet 13 of 15

Place U12 close to R1



Place U13 close to R2



Current Sensing for DLPC910

DATE	3/18/2015	TEXAS INSTRUMENTS - DLP?Products
DESIGNER		
TITLE		TIDA-00570 High Speed DLP Subsystem DLPC910 Main Board
PROJECT		DLPC910
DOC		2514435
T12.17 Circuit Capture VLS		SHEET 14 of 15

Revisions

Rev. A : Initial Release

REVISION NOTES

DATE	3/18/2015	TEXAS INSTRUMENTS - DLP7Products	
DESIGN		© COPYRIGHT 2015 Texas Instruments Inc. All Rights Reserved	
TITLE		TIDA-00570 High Speed DLP Sub-system DLP3010 Mask Board	
DESIGNED BY		DRAWING NO	2514435
DATE		11 & 17	Sheet Count: 15 & 15
			SECRET 15 of 15